Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK2844

Chopper Regulator, DC-DC Converter and Motor Drive Applications

4 V gate drive

• Low drain-source ON resistance : RDS (ON) = 16 m Ω (typ.)

• High forward transfer admittance $: |Y_{fs}| = 26 \text{ S (typ.)}$ • Low leakage current $: I_{DSS} = 100 \text{ } \mu\text{A (max) (V}_{DS} = 30 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	30	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	30	V	
Gate-source voltage		V_{GSS}	±20	٧	
Drain current	DC (Note 1)	I _D	35	Α	
	Pulse (Note 1)	I_{DP}	140	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	60	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	259	mJ	
Avalanche current		I _{AR}	35	Α	
Repetitive avalanche	energy (Note 3)	E _{AR}	6	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

10.3MAX. #3.6±0.2 10.3MAX. #3.6±0.2 1.6MAX. #3

Weight: 2.0 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.08	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 152 μ H, R_{G} = 25 Ω , I_{AR} = 35 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

2SK2844



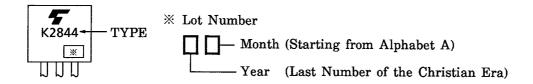
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ	
Drain cut-off cu	rent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	100	μΑ	
Drain-source br	eakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_	_	V	
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V	
Drain-source ON resistance		R _{DS} (ON)	V _{GS} = 4 V, I _D = 18 A	_	26	35	mΩ	
			V _{GS} = 10 V, I _D = 18 A		16	20		
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 18 A	13	26	_	S	
Input capacitano	e	C _{iss}		_	980	_		
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	270	_	pF	
Output capacitance		Coss			580	_		
Switching time	Rise time	t _r	V_{GS} $0V$ $R_{L}=0.8\Omega$ $V_{DD}=14.4V$	_	14	_	ns	
	Turn-on time	t _{on}		_	23	_		
	Fall time	t _f		_	64			
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_	190	_		
Total gate charg plus gate-drain)	,		_	40	_			
Gate-source charge		Q_{gs}	$V_{DD} \approx 24 \text{ V, } V_{GS} = 10 \text{ V, } I_{D} = 35 \text{ A}$		32	_	nC	
Gate-drain ("miller") Charge		Q_{gd}			8			

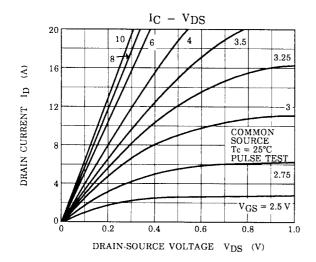
Source-Drain Ratings and Characteristics (Ta = 25°C)

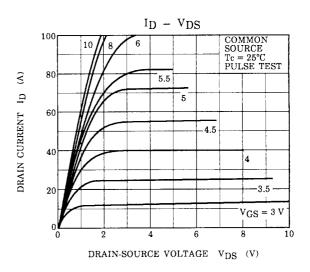
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	50	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_		_	200	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 35 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 35 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / μs	_	120	_	ns
Reverse recovery charge	Q _{rr}	1DR - 33 Λ, VGS - 0 V, αιDR / αι - 30 Α / μs	_	180	_	nC

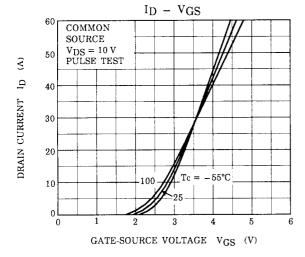
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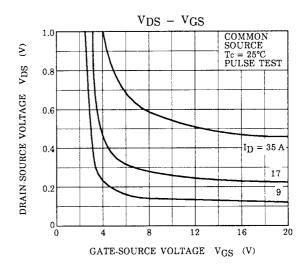


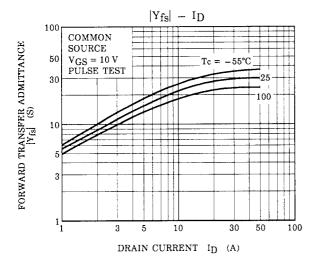
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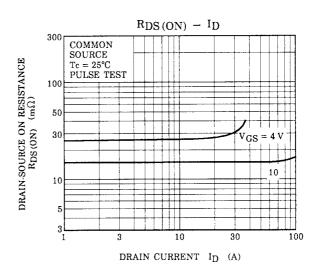




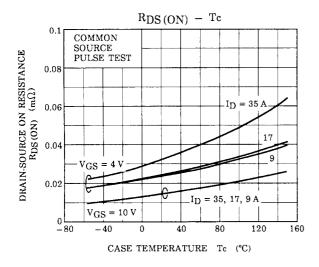


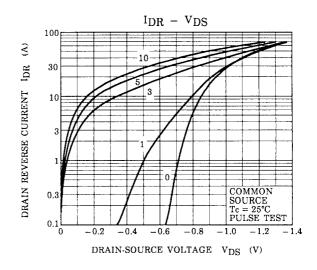


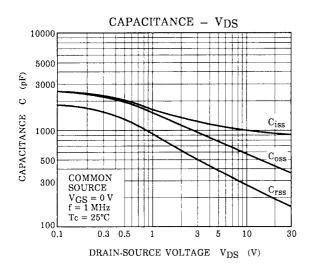


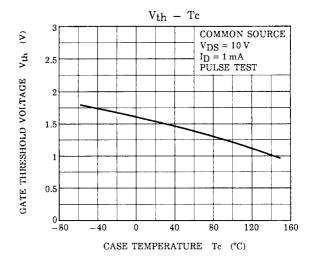


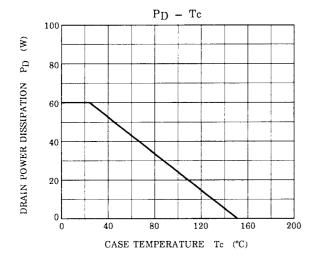
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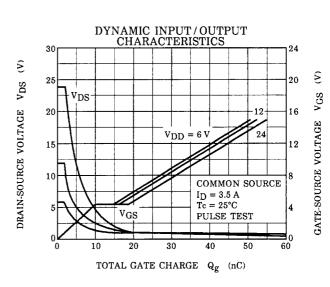




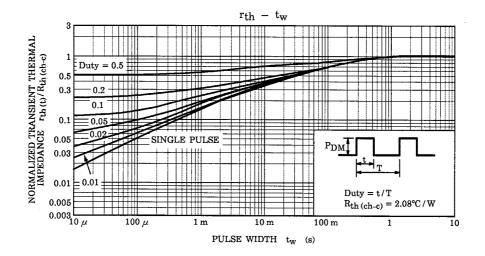


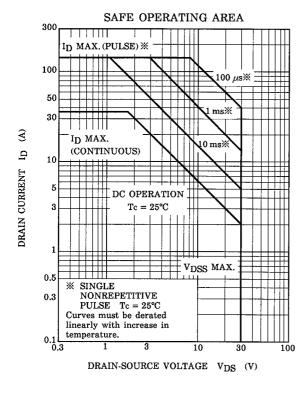


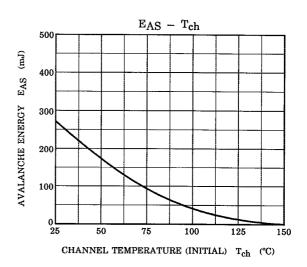


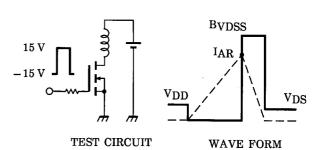


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$$R_G$$
 = 25 Ω
 V_{DD} = 25 V, L = 152 μH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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